Applicant: Brintzinger et al.
For: Method for the Solder-Stop Structuring of Elevations on Wafers
Docket No. A35975-066340.0175
Atty: Robert L. Maier
Tel. (212) 408-2538

1/2

FIG 1 10

FIG 2

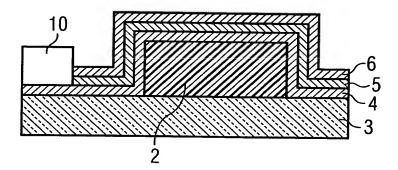
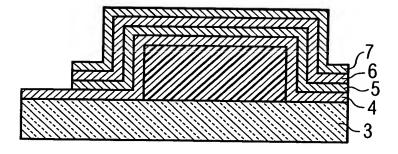


FIG 3



Applicant: Brintzinger et al.
For: Method for the Solder-Stop Structuring of Elevations on Wafers
Docket No. A35975-066340.0175
Atty: Robert L. Maier
Tel. (212) 408-2538

2/2

FIG 4

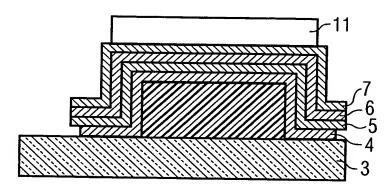


FIG 5

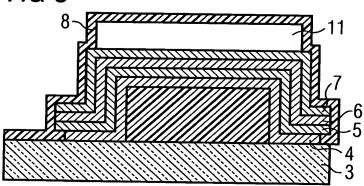


FIG 6

